



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-06-10
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
BAS70-05FILM	HJWT*NHBAR28	A	Z55A	2016-06-10
Amount		UoM	Unit type	ST ECOPACK Grade
10.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Alloy 42		



Package Designator	Size	Nbr of instances	Shape	
DSO	2.8 - 1.4 - 1	3	gull wing	
Comment	Package: SOT 23 CATHODE COMMUNE			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HJWTHBAR28					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.202	mg	supplier	die	Silicon (Si)	7440-21-3		0.176	mg	870425	17600
				supplier	metallization	Aluminium (Al)	7429-90-5		0.024	mg	118694	2400
				supplier	Passivation	Silicon Oxide	7631-86-9		0.002	mg	9892	200
				supplier	back side metallization	Gold (Au)	7440-57-5		0.000	mg	989	20
Leadframe	Copper & its alloys	3.003	mg	Supplier	Alloy	Iron (Fe)	7439-89-6		1.668	mg	555445	166800
				Supplier	Alloy	Nickel (Ni)	7440-02-0		1.182	mg	393606	118200
				Supplier	Alloy	Manganese (Mn)	7439-96-5		0.018	mg	5994	1800
				Supplier	Alloy	Cobalt (Co)	7440-48-4		0.014	mg	4662	1400
				Supplier	metallization	Silver (Ag)	7440-22-4		0.121	mg	40293	12100
				Supplier	Bonding wire	Gold (Au)	7440-57-5		0.031	mg	1000000	3100
Encapsulation	Other organic materials	6.462	mg	Supplier	Moulding Compound	silica vitreous	60676-86-0		5.512	mg	852987	551200
				Supplier	Moulding Compound	Epoxy Cresol Novolak	29690-82-2		0.355	mg	54937	35500
				Supplier	Moulding Compound	Phenol Resin	26834-02-6		0.323	mg	49983	32300
				Supplier	Moulding Compound	Tetrakis(2,6-dimethylphenyl) 1,3-phenylene bi	139189-30-3		0.162	mg	25070	16200
				Supplier	Moulding Compound	Carbon black	1333-86-4		0.013	mg	2012	1300
Finishing	Solder	0.302	mg	Supplier	Moulding Compound	Biphenyl epoxy resin	85954-11-6		0.097	mg	15011	9700
				Supplier	Connection coating	Tin (Sn)	7440-31-5		0.302	mg	1000000	30200